CLAIMS

1. A component-manufacturing tool used in a method of a semiconductor component or a method of an electronic component, the tool comprising:

a frame body having an opening; and a holding film stretched on the frame body so as to cover the opening, wherein:

the frame body includes a ring-shaped first frame, and a ring-shaped second frame capable of being engaged with the first frame;

the holding film includes a base layer and a holding layer provided on one surface of the base layer, and is sandwiched and held between the first frame and the second frame in a stretched state; and

a ratio R_{E1}(= E'(100)/E'(25)) of an elastic modulus E'(100) at 100°C of the base layer to an elastic modulus E'(25) at 25°C of the base layer is $\underline{0.30}\sout{0.2} \leq R_{E1} \leq 1$, and E'(25) is 35 MPa or more and 3500 MPa or less.

2. The component-manufacturing tool according to claim 1, wherein a linear thermal expansion coefficient of the base layer is 100 ppm/K or more.

3. The component-manufacturing tool according to claim 1 or 2, wherein the base layer contains at least one of a thermoplastic polyester-based elastomer, a thermoplastic polyamide-based elastomer, and polybutylene terephthalate.

4. The component-manufacturing tool according to any one of claims 1 to 3, wherein the manufacturing method comprises a chucking step where the holding film, to the holding layer of which a plurality of components selected from a semiconductor component, a precursor of the semiconductor component, an electronic component, and a precursor of the electronic component are held, is chucked and fixed to a surface of a heated chuck table.

5. The component-manufacturing tool according to claim 4, wherein the manufacturing method comprises, after the chucking step, an evaluation step where the components held to the holding film are evaluated.

6. The component-manufacturing tool according to claim 5, wherein the manufacturing method comprises, after the evaluation step, a pickup step where only a part of the components is pushed from a side of the base layer toward a side of the holding layer to further stretch the holding film, so that the component is separated from the other components and is picked up.

7. A component-manufacturing method comprising:

a component holding step where a plurality of components selected from a semiconductor component, a precursor of the semiconductor component, an electronic component, and a precursor of the electronic component are held to a holding layer of a component-manufacturing tool that includes

a frame body having an opening, and a holding film stretched on the frame body so as to cover the opening,

the frame body including a ring-shaped first frame and a ring-shaped second frame capable of being engaged with the first frame,

the holding film including a base layer and the holding layer provided on one surface of the base layer and being sandwiched and held between the first frame and the second frame in a stretched state, and

a ratio R_{E1}(= E'(100)/E'(25)) of an elastic modulus E'(100) at 100°C of the base layer to an elastic modulus E'(25) at 25°C of the base layer being ~~0.2~~0.30 ≤R_{E1} ≤ 1 and E'(25) being 35 MPa or more and 3500 MPa or less; and

a chucking step where the holding film, to which the components are held, is chucked and fixed to a surface of a heated chuck table.

8. The component-manufacturing method according to claim 7, comprising, after the chucking step, an evaluation step where the components held to the holding film are evaluated.

9. The component-manufacturing method according to claim 8, comprising, after the evaluation step, a pickup step where only a part of the components is pushed from a side of the base layer toward a side of the holding layer to further stretch the holding film, so that the component is separated from the other components and is picked up.